

**BYV255V**

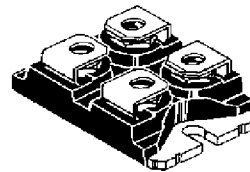
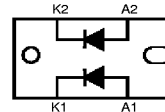
HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

FEATURES

- SUITED FOR SMPS
- VERY LOW FORWARD LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY
- INSULATED :
Insulating voltage = 2500 V_{RMS}
Capacitance = 55 pF

DESCRIPTION

Dual rectifier suited for switchmode power supply and high frequency DC to DC converters. Packaged in ISOTOP™ this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



ISOTOP
(Plastic)

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Value	Unit
$I_{F(RMS)}$	RMS forward current		Per diode	150	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	$T_c = 110^\circ\text{C}$	Per diode	100	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ms}$ sinusoidal	Per diode	1600	A
T_{stg} T_j	Storage and junction temperature range			- 40 to + 150 - 40 to + 150	$^\circ\text{C}$ $^\circ\text{C}$

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	200	V

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THERMAL RESISTANCE

Symbol	Parameter		Value	Unit
Rth (j-c)	Junction to case	Per diode	0.4	°C/W
		Total	0.25	
Rth (c)	Coupling		0.1	°C/W

When the diodes 1 and 2 are used simultaneously :

$$T_j - T_c (\text{diode 1}) = P(\text{diode 1}) \times R_{th}(j-c)(\text{Per diode}) + P(\text{diode 2}) \times R_{th}(c)$$

ELECTRICAL CHARACTERISTICS (Per diode) STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I_R *	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			100	μA
	$T_j = 100^\circ\text{C}$				10	mA
V_F **	$T_j = 125^\circ\text{C}$	$I_F = 100\text{ A}$			0.85	V
	$T_j = 125^\circ\text{C}$	$I_F = 200\text{ A}$			1.00	
	$T_j = 25^\circ\text{C}$	$I_F = 200\text{ A}$			1.15	

Pulse test : * $t_p = 5\text{ ms}$, duty cycle $< 2\%$

** $t_p = 380\text{ }\mu\text{s}$, duty cycle $< 2\%$

To evaluate the conduction losses use the following equation :

$$P = 0.7 \times I_{F(AV)} + 0.0015 \times I_F^2(\text{RMS})$$

RECOVERY CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
trr	$T_j = 25^\circ\text{C}$	$I_F = 0.5\text{ A}$ $I_{rr} = 0.25\text{ A}$ $I_R = 1\text{ A}$			55	ns
		$I_F = 1\text{ A}$ $dI_F/dt = -50\text{ A}/\mu\text{s}$ $V_R = 30\text{ V}$			80	
tfr	$T_j = 25^\circ\text{C}$	$I_F = 1\text{ A}$ $t_r = 5\text{ ns}$ $V_{FR} = 1.1 \times V_F$		10		ns
V_{FP}	$T_j = 25^\circ\text{C}$	$I_F = 1\text{ A}$ $t_r = 5\text{ ns}$		1.5		V

TURN-OFF SWITCHING CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
I_{RM}	$T_j = 100^\circ\text{C}$	$I_F = 100\text{ A}$ $L_p \leq 0.05\text{ }\mu\text{H}$ $V_{CC} \leq 0.6 V_{RRM}$	$dI_F/dt = -200\text{ A}/\mu\text{s}$		16	A
			$dI_F/dt = -400\text{ A}/\mu\text{s}$	24		

Fig.1 : Average forward power dissipation versus average forward current.

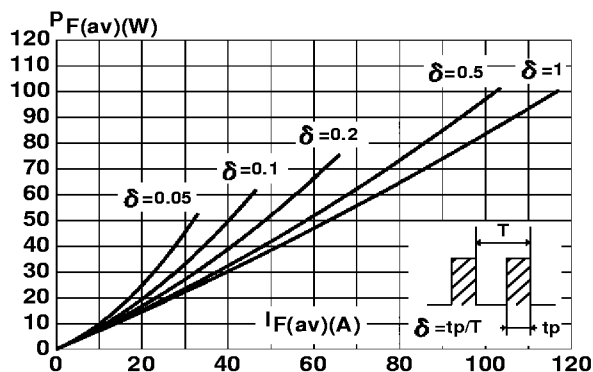


Fig.2 : Peak current versus form factor.

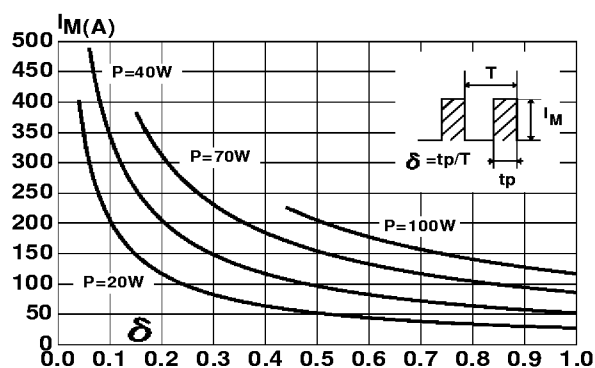


Fig.3 : Forward voltage drop versus forward current (maximum values).

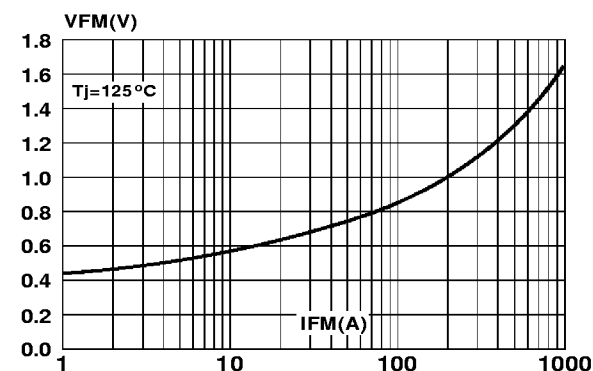


Fig.4 : Relative variation of thermal impedance junction to case versus pulse duration.

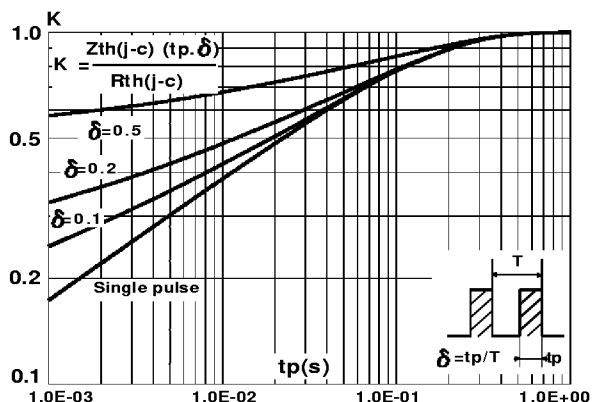


Fig.5 : Non repetitive surge peak forward current versus overload duration.

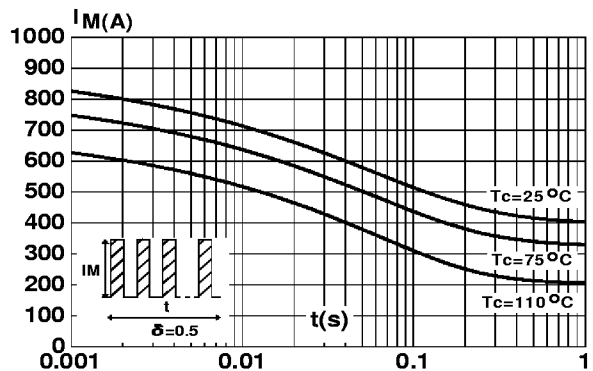


Fig.6 : Average current versus ambient temperature. (duty cycle : 0.5)

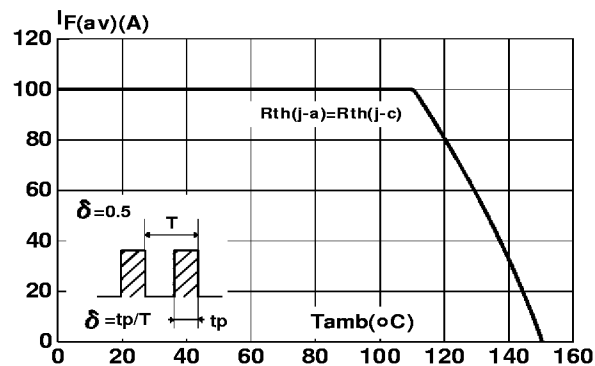


Fig.7 : Junction capacitance versus reverse voltage applied (Typical values).

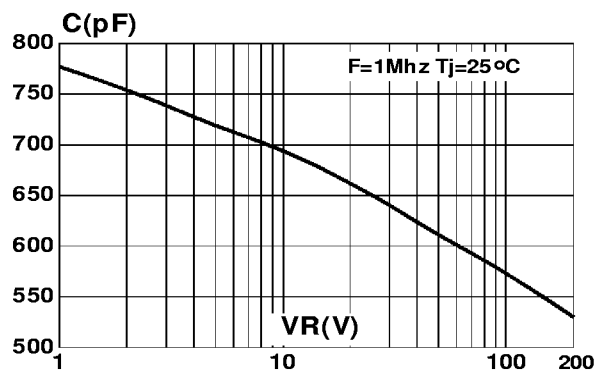


Fig.9 : Peak reverse current versus dI_F/dt .

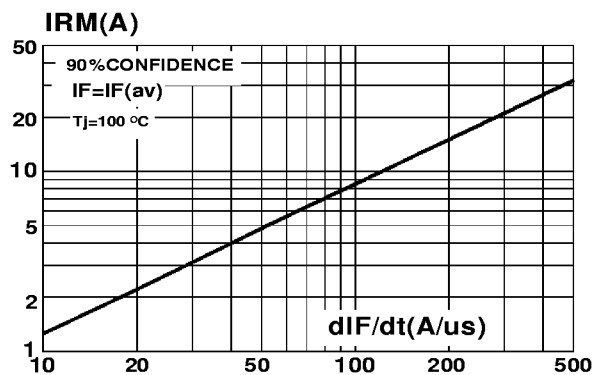


Fig.8 : Recovery charges versus dI_F/dt .

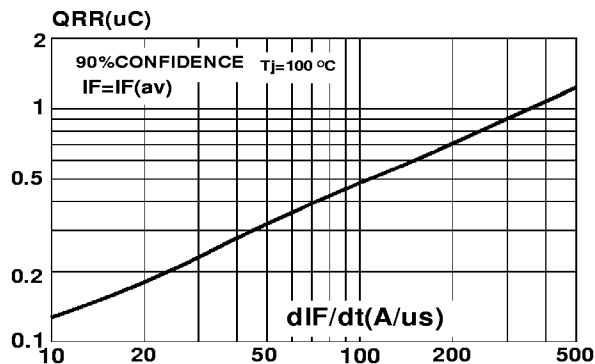
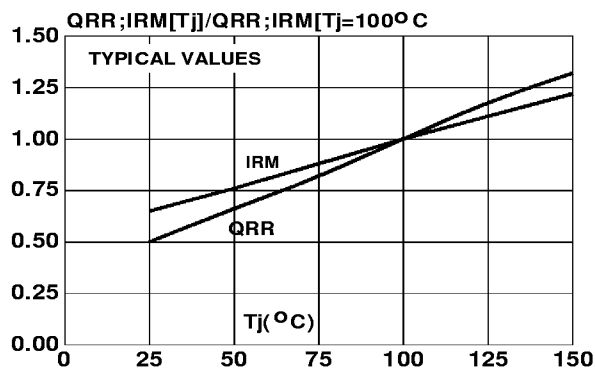
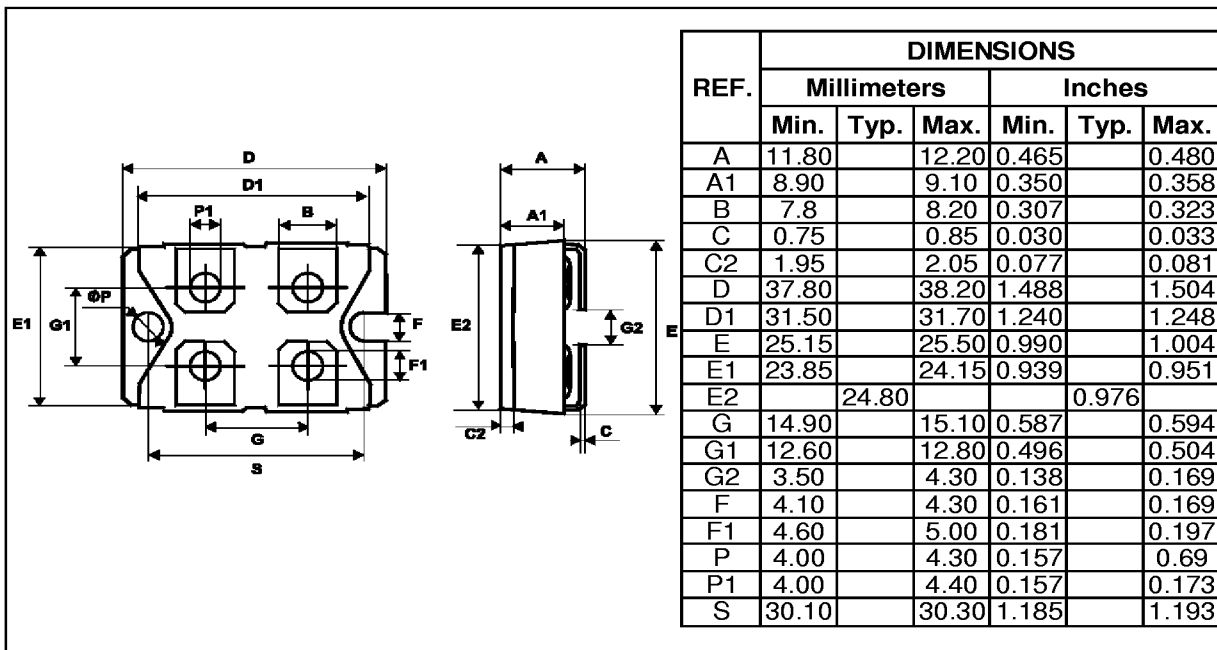


Fig.10 : Dynamic parameters versus junction temperature.



PACKAGE MECHANICAL DATA **ISOTOP**



- **Marking** : Type number
- **Cooling method** : C
- **Weight** : 27 g

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